



SOT1145-1

plastic thin fine-pitch ball grid array package; 385 balls, 0.5 mm pitch, 12 mm x 12 mm x 0.81 mm body

19 August 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA385
Package type industry code	TFBGA385
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-08-2009
Manufacturer package code	SOT1145

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	11.9	12	12.1	mm
package width	11.9	12	12.1	mm
seated height	0.95	1.06	1.2	mm
package height	0.75	0.81	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	385	-	



3 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Legal information3